



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Jau-Shoung CHEN et al. Confirmation No: 4031
Appl. No. : 10/693,896
Filed : October 28, 2003
Title : WAFER BUMPING PROCESS WITH SOLDER BALLS
BONDED TO UNDER BUMP METALLURGY LAYER
FORMED OVER ACTIVE SURFACE BY FORMING
FLUX ON SOLDER BALL SURFACES
AND REFLOWING THE SOLDER
TC/A.U. : 2813
Examiner : Stephen W. Smoot
Docket No.: : CHEN3595/REF
Customer No: : 23364

REQUEST FOR CLARIFICATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In reviewing the application prior to paying the issue fee, Applicants have advised the undersigned attorney that there is a typographical error in the title of the application as shown on PTOL 85. The title was changed to "Wafer Bumping Process With Solder Balls Bonded To Under Bump Metallurgy Layer Formed Over Active Surface By Forming Flux On Solder Ball Surfaces And Reflowing The Solder" with an Amendment filed on April 26, 2005 and has been accepted by the Examiner.

Appl. No. 10/693,896
Request dated: July 29, 2005
Reply to OA of: May 11, 2005

Please ensure that the correct title with the word "active" and not the word "acti"
as present on the issue fee form appears on the printed patent.

Respectfully submitted,

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